











TLV61046A

ZHCSGJ6A - APRIL 2017 - REVISED APRIL 2017

具有功率二极管和隔离开关的 TLV61046A 28V 输出电压升压转换器

1 特性

- 输入电压范围: 1.8V 至 5.5V, 启动后为降为 1.6V
- 输出电压高达 28V
- 集成有功率二极管和隔离开关
- 开关电流为 980mA (典型值)
- 输入电压为 3.6V、输出电压为 12V 时,效率高达 85%
- 输出电压精度为 ±2.5%
- 轻负载状态下进入节能工作模式
- 内部 7ms 软启动时间
- 关断时输入与输出真正断开
- 输出短路保护
- 输出过压保护
- 热关断保护
- 3mm x 3mm SOT23-6 封装

2 应用

- PMOLED 电源
- LCD 面板
- 可穿戴式设备
- 便携式医疗设备
- 传感器电源

3 说明

TLV61046A 是一款高度集成型升压转换器,专为 PMOLED 面板、LCD 偏置电源和传感器模块等 应用 而设计。TLV61046A 集成了 30V 电源开关、输入至输 出的隔离开关以及整流器二极管。该器件可将来自一节 锂离子电池或两节碱性电池(串联)的输入电压转换成 高达 28V 的输出电压。

TLV61046A 的工作开关频率为 1.0MHz。该器件支持使用小型外部组件。通过将 TLV61046A 的 FB 引脚和 VIN 引脚相连,可将其默认内部输出电压设置为 12V。因此,只需要三个外部组件即可获得 12V 输出电压。TLV61046A 的开关限流典型值为 980mA。它具有 7ms 内置软启动时间,从而能够降低浪涌电流。TLV61046A 处于关断模式时,隔离开关会将输出与输入断开以最大限度降低泄漏电流。TLV61046A 还具有输出短路保护、输出过压保护和热关断。

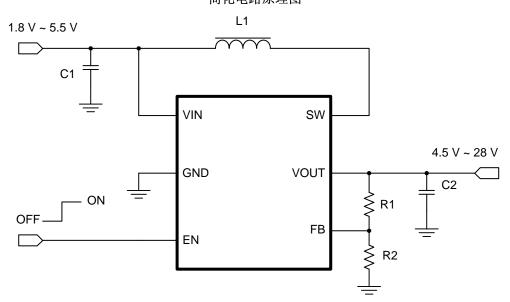
TLV61046A 采用 6 引脚, 3mm x 3mm SOT23-6 封装。

器件信息(1)

器件型号	封装	封装尺寸 (标称值)
TLV61046A	SOT23-6 (6)	2.9mm x 1.6mm

(1) 要了解所有可用封装,请参阅数据表末尾的可订购产品附录。

简化电路原理图



Copyright © 2017, Texas Instruments Incorporated



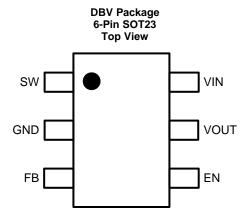
	目表	录		
1	特性	8	Application and Implementation	. 1
2	应用 1		8.1 Application Information	1
3	说明1		8.2 Typical Application - 12-V Output Boost Converte	r 1
4	修订历史记录 2		8.3 System Examples	1
5	Pin Configuration and Functions		Power Supply Recommendations	
6	Specifications4	10	Layout	17
-	6.1 Absolute Maximum Ratings 4		10.1 Layout Guidelines	
	6.2 ESD Ratings 4		10.2 Layout Example	
	6.3 Recommended Operating Conditions 4	11	器件和文档支持	
	6.4 Thermal Information		11.1 器件支持	
	6.5 Electrical Characteristics5		11.2 接收文档更新通知	18
	6.6 Typical Characteristics		11.3 社区资源	18
7	Detailed Description8		11.4 商标	
	7.1 Overview 8		11.5 静电放电警告	
	7.2 Functional Block Diagram8		11.6 Glossary	
	7.3 Feature Description9	12	机械、封装和可订购信息	18
	7.4 Device Functional Modes9			

4 修订历史记录

CI	hanges from Original (April 2017) to Revision A	Page
•	已更改 更改为"牛产数据"	1



5 Pin Configuration and Functions



Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NUMBER	ITFE	DESCRIPTION
SW	1	PWR	The switch pin of the converter. It is connected to the drain of the internal power MOSFET.
GND	2	PWR	Ground
FB	3	Ι	Voltage feedback of adjustable output voltage. Connected to the center tap of a resistor divider to program the output voltage. When it is connected to the VIN pin, the output voltage is set to 12 V by an internal feedback.
EN	4	I	Enable logic input. Logic high voltage enables the device. Logic low voltage disables the device and turns it into shutdown mode.
VOUT	5	PWR	Output of the boost converter
VIN	6	I	IC power supply input



6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) (1)

		MIN	MAX	UNIT
Voltage range at terminals (2)	VIN, EN, FB	- 0.3	6	V
Voltage range at terminals (2)	SW, VOUT	-0.3	32	V
Operating junction temperature range, T _J		-40	150	°C
Storage temperature range, T _{stg}		-65	150	°C

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to network ground terminal.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD) (1)		Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins (2)		V
	Electrostatic discharge	Charged device model (CDM), per JEDEC specification JESD22-C101, all $pins^{(3)}$	±500	V

Electrostatic discharge (ESD) to measure device sensitivity and immunity to damage caused by assembly line electrostatic discharges in to the device.

- (2) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (3) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	TYP	MAX	UNIT
V_{IN}	Input voltage range	1.8		5.5	V
V _{OUT}	Output voltage range	3.3		28	V
L	Effective inductance range	2.2×0.7	10	22×1.3	μΗ
C _{IN}	Effective input capacitance range	0.22	1.0		μF
C _{OUT}	Effective output capacitance range	0.22	1.0	10	μF
TJ	Operating junction temperature	-40		125	°C

6.4 Thermal Information

		TLV61046A	
	THERMAL METRIC ⁽¹⁾	DBV (SOT23)	UNIT
		6 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	177.7	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	120.6	
$R_{\theta JB}$	Junction-to-board thermal resistance	33.2	°C/W
ΨЈТ	Junction-to-top characterization parameter	21.5	*C/vv
ΨЈВ	Junction-to-board characterization parameter	32.6	
R ₀ JC(bot)	Junction-to-case (bottom) thermal resistance	n/a	

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



6.5 Electrical Characteristics

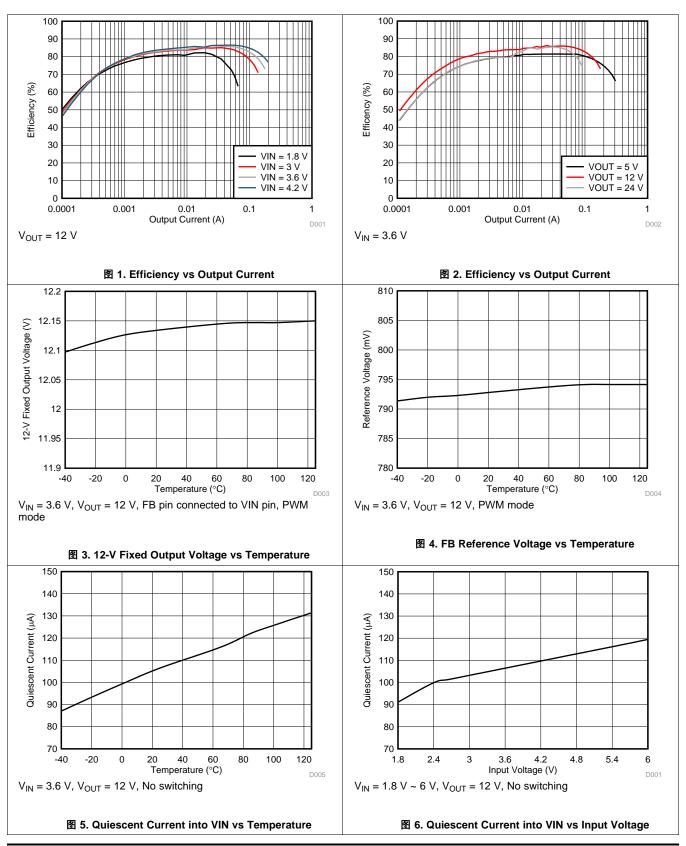
 $T_A = -40$ °C to 85 °C, $V_{IN} = 3.6$ V and $V_{OUT} = 12$ V. Typical values are at $T_A = 25$ °C, unless otherwise noted.

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER S	UPPLY					
V _{IN}	Input voltage range		1.8		5.5	V
		V _{IN} rising		1.75	1.8	.,
V _{IN_UVLO}	Under voltage lockout threshold	V _{IN} falling		1.55	1.6	V
V _{IN_HYS}	VIN UVLO hysteresis			200		mV
$I_{Q_{-}VIN}$	Quiescent current into VIN pin	IC enabled, no load, no switching, V_{IN} = 1.8 V to 5.5 V, V_{OUT} = 12 V		110	200	μΑ
I _{SD}	Shutdown current into VIN pin	IC disabled, V _{IN} = 1.8 V to 5.5 V, T _A = 25°C	·	0.1	1.0	μΑ
OUTPUT			•		,	
V _{OUT}	Output voltage range		3.3		28	V
V _{OUT_12V}	12-V output voltage accuracy	FB pin connected to VIN pin, T _J =0°C to 125°C	11.7	12.1	12.4	V
		PWM mode, T _A =25°C	0.783	0.795	0.807	V
V_{REF}	Feedback voltage	PWM mode, T _J =-40°C to 125°C	0.775	0.795	0.815	V
		PFM mode, T _A =25°C	·	0.803		V
V _{OVP}	Output overvoltage protection threshold		28	29.2	30.4	V
V _{OVP_HYS}	Over voltage protection hysteresis			0.9		V
I _{FB_LKG}	Leakage current into FB pin	T _A = 25°C	·		200	nA
I _{SW_LKG}	Leakage current into SW pin	IC disabled, T _A = 25°C			500	nA
POWER S	WITCH					
D	Isolation MOSFET on resistance	V _{OUT} = 12 V		850		0
R _{DS(on)}	Low-side MOSFET on resistance	V _{OUT} = 12 V		450		mΩ
f _{SW}	Switching frequency	V _{IN} = 3.6 V, V _{OUT} = 12 V, PWM mode	850	1050	1250	kHz
t _{ON_min}	Minimal switch on time			150	250	ns
	Dook quitab augrant limit	V _{IN} = 3.6 V, V _{OUT} = 12 V	680	980	1250	mA
I _{LIM_SW}	Peak switch current limit	$V_{IN} = 2.4 \text{ V}, V_{OUT} = 3.3 \text{ V}$	20			mA
I _{LIM_CHG}	Pre-charge current	$V_{IN} = 3.6 \text{ V}, V_{OUT} = 0 \text{ V}$	·	30	50	mA
t _{STARTUP}	Startup time	V_{OUT} from V_{IN} to 12 V, $C_{OUT_effective}$ = 2.2 μ F, I_{OUT} = 0 A	2	5		ms
LOGIC IN	TERFACE		·			
V _{EN_H}	EN Logic high threshold				1.2	V
V_{EN_L}	EN Logic Low threshold		0.4			V
PROTECT	TION					
T _{SD}	Thermal shutdown threshold	T _J rising		150		°C
T _{SD_HYS}	Thermal shutdown hysteresis	T _J falling below T _{SD}		20		°C

TEXAS INSTRUMENTS

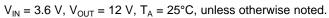
6.6 Typical Characteristics

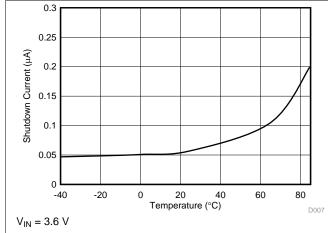
 $V_{IN} = 3.6 \text{ V}, V_{OUT} = 12 \text{ V}, T_A = 25^{\circ}\text{C}, \text{ unless otherwise noted.}$





Typical Characteristics (接下页)





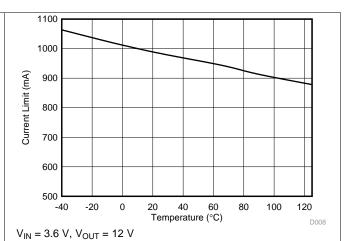


图 7. Shutdown Current vs Temperature

图 8. Current Limit vs Temperature

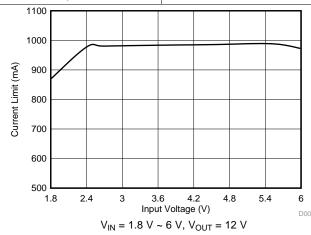


图 9. Current Limit vs Input Voltage



7 Detailed Description

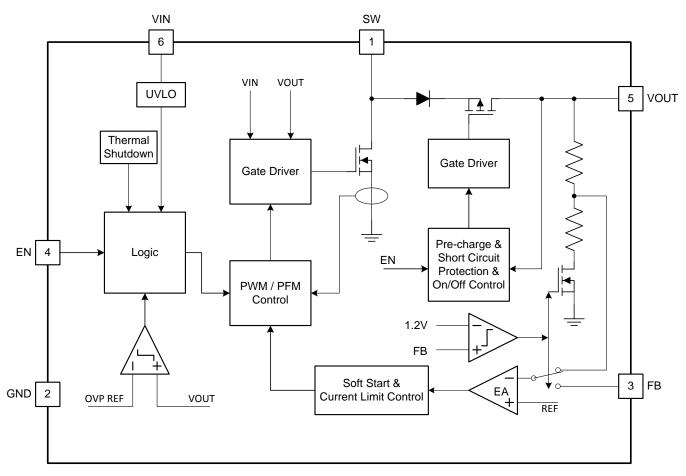
7.1 Overview

The TLV61046A is a highly integrated boost converter designed for applications requiring high voltage and small solution size such as PMOLED panel power supply and sensor module. The TLV61046A integrates a 30-V power switch, an input to output isolation switch and a rectifier diode. It can output up to 28 V from input of a Li+battery or two cell alkaline batteries in series.

One common issue with conventional boost regulators is the conduction path from input to output even when the power switch is turned off. It creates three problems, which are inrush current during start-up, output leakage current during shutdown and excessive over load current. In the TLV61046A, the isolation switch is turned off under shutdown mode and over load conditions, thereby opening the current path. Thus the TLV61046A can truely disconnect the load from the input voltage and minimize the leakage current during shutdown mode.

The TLV61046A operates with a switching frequency at 1.0 MHz. This allows the use of small external components. The TLV61046A has an internal default 12-V output voltage setting by connecting the FB pin to the VIN pin. Thus it only needs three external components to get 12-V output voltage. The TLV61046A has typical 980-mA switch current limit. It has 7-ms built-in soft start time to minimize the inrush current. The TLV61046A also implements output short circuit protection, output over-voltage protection and thermal shutdown.

7.2 Functional Block Diagram



Copyright © 2016, Texas Instruments Incorporated



7.3 Feature Description

7.3.1 Under-Voltage Lockout

An under-voltage lockout (UVLO) circuit stops the operation of the converter when the input voltage drops below the typical UVLO threshold of 1.55 V. A hysteresis of 200 mV is added so that the device cannot be enabled again until the input voltage goes up to 1.75 V. This function is implemented in order to prevent malfunctioning of the device when the input voltage is between 1.55 V and 1.75 V.

7.3.2 Enable and Disable

When the input voltage is above maximal UVLO rising threshold of 1.8 V and the EN pin is pulled high, the TLV61046A is enabled. When the EN pin is pulled low, the TLV61046A goes into shutdown mode. The device stops switching and the isolation switch is turned off providing the isolation between input and output. In shutdown mode, less than 1-µA input current is consumed.

7.3.3 Soft Start

The TLV61046A begins soft start when the EN pin is pulled high. at the beginning of the soft start period, the isolation FET is turned on slowly to charge the output capacitor with 30-mA current for about 2 ms. This is called the pre-charge phase. After the pre-charge phase, the TLV61046A starts switching. This is called switching soft start phase. An internal soft start circuit limits the peak inductor current according to the output voltage. When the output voltage is below 3 V, the peak inductor current is limited to 140 mA. Along with the output voltage going up from 3 V to 5 V, the peak current limit is gradually increased to the normal value of 980 mA. The switching soft start phase is about 5 ms typically. The soft start funciton reduces the inrush current during startup.

7.3.4 Over-voltage Protection

The TLV61046A has internal output over-voltage protection (OVP) function. When the output voltage exceeds the OVP threshold of 29.2 V, the device stops switching. Once the output voltage falls 0.9 V below the OVP threshold, the device resumes operation again.

7.3.5 Output Short Circuit Protection

The TLV61046A starts to limit the output current whenever the output voltage drops below 4 V. The lower output voltage, the smaller output current limit. When the VOUT pin is shorted to ground, the output current is limited to less than 200 mA. This function protects the device from being damaged when the output is shorted to ground.

7.3.6 Thermal Shutdown

The TLV61046A goes into thermal shutdown once the junction temperature exceeds the thermal shutdown termperature threshold of 150°C typically. When the junction temperature drops below 130°C typically, the device starts operating again.

7.4 Device Functional Modes

The TLV61046A has two operation modes, PWM mode and power save mode.

7.4.1 PWM Mode

The TLV61046A uses a quasi-constant 1.0-MHz frequency pulse width modulation (PWM) at moderate to heavy load current. Based on the input voltage to output votlage ratio, a circuit predicts the required off-time. At the beginning of the switching cycle, the NMOS switching FET, shown in the functional block diagram, is turned on. The input voltage is applied across the inductor and the inductor current ramps up. In this phase, the output capacitor is discharged by the load current. When the inductor current hits the current threshold that is set by the output of the error amplifier, the PWM switch is turned off, and the power diode is forward-biased. The inductor transfers its stored energy to replenish the output capacitor and supply the load. When the off-time is expired, the next switching cycle starts again. The error amplifier compares the FB pin voltage with an internal reference votlage, and its output determines the inductor peak current.

The TLV61046A has a built-in compensation circuit that can accommodate a wide range of input voltage, output voltage, inductor value and output capacitor value for stable operation.



Device Functional Modes (接下页)

7.4.2 Power Save Mode

The TLV61046A implements a power save mode with pulse frequency modulation (PFM) to improve efficiency at light load. When the load current decreases, the inductor peak current set by the output of the error amplifier declines to regulate the output voltage. When the inductor peak current hits the low limit of 200 mA, the output voltage will exceed the setting voltage as the load current decreases further. When the FB voltage hits the PFM reference voltage, the TLV61046A goes into the power save mode. In the power save mode, when the FB voltage rises and hits the PFM reference voltage, the device continues switching for several cycles because of the delay time of the internal comparator. Then it stops switching. The load is supplied by the output capacitor and the output voltage declines. When the FB voltage falls below the PFM reference voltage, after the delay time of the comparator, the device starts switching again to ramp up the output voltage.

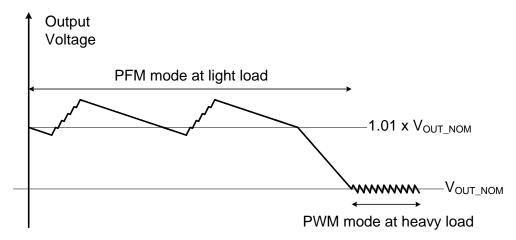


图 10. Output Voltage in PWM Mode and PFM Mode



8 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The TLV61046A is a boost DC-DC converter integrating a power switch, an input to output isolation switch and a rectifier diode. The device supports up to 28-V output with the input voltage range from 1.8 V to 5.5 V. The TLV61046A adopts the current-mode control with adaptive constant off-time. The switching frequency is quasiconstant at 1.0 MHz. The isolation switch disconnects the output from the input during shutdown to minimize leakage current.

The following design procedure can be used to select component values for the TLV61046A.

8.2 Typical Application - 12-V Output Boost Converter

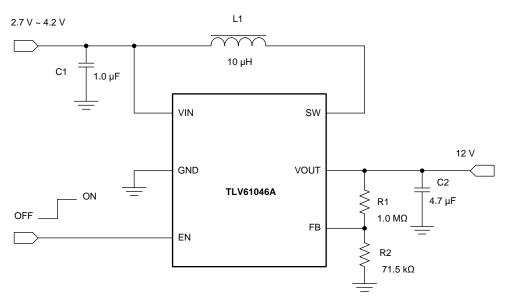


图 11. 12-V Boost Converter

8.2.1 Design Requirements

表 1. Design Requirements

PARAMETERS	VALUES
Input Voltage	2.7 V ~ 4.2 V
Output Voltage	12 V
Output Current	50 mA
Output Voltage Ripple	±50mV



8.2.2 Detailed Design Procedure

8.2.2.1 Programming the Output Voltage

There are two ways to set the output voltage of the TLV61046A. When the FB pin is connected to the input voltage, the output voltage is fixed to 12 V. This function makes the TLV61046A only need three external components to minimize the solution size. The second way is to use an external resistor divider to set the desired output voltage.

By selecting the external resistor divider R1 and R2, as shown in $\Delta \pm 1$, the output voltage is programmed to the desired value. When the output voltage is regulated, the typical voltage at the FB pin is V_{RFF} of 795 mV.

$$R1 = \left(\frac{V_{OUT}}{V_{REF}} - 1\right) \times R2$$

where

- V_{OUT} is the desired output voltage
- V_{REF} is the internal reference voltage at the FB pin

For best accuracy, R2 should be kept smaller than 80 k Ω to ensure the current flowing through R2 is at least 100 times larger than the FB pin leakage current. Changing R2 towards a lower value increases the immunity against noise injection. Changing the R2 towards a higher value reduces the quiescent current for achieving higher efficiency at low load currents.

8.2.2.2 Inductor Selection

Because the selection of the inductor affects steady state operation, transient behavior, and loop stability, the inductor is the most important component in power regulator design. There are three important inductor specifications, inductor value, saturation current, and dc resistance (DCR).

The TLV61046A is designed to work with inductor values between 2.2 μ H and 22 μ H. Follow 公式 2 to 公式 4 to calculate the inductor's peak current for the application. To calculate the peak current in the worst case, use the minimum input voltage, maximum output voltage, and maximum load current of the application. To have enough design margin, choose the inductor value with -30% tolerance, and a low power-conversion efficiency for the calculation.

In a boost regulator, the inductor dc current can be calculated with 公式 2.

$$I_{L(DC)} = \frac{V_{OUT} \times I_{OUT}}{V_{IN} \times \eta}$$

where

- V_{OUT} = output voltage
- I_{OUT} = output current
- V_{IN} = input voltage
- η = power conversion efficiency, use 80% for most applications

The inductor ripple current is calculated with the $\triangle \exists$ 3 for an asynchronous boost converter in continuous conduction mode (CCM).

$$\Delta I_{L(P-P)} = \frac{V_{IN} \times (V_{OUT} + 0.8V - V_{IN})}{L \times f_{SW} \times (V_{OUT} + 0.8V)}$$

where

- $\Delta I_{L(P-P)}$ = inductor ripple current
- L = inductor value
- f_{SW} = switching frequency
- V_{OUT} = output voltage
- V_{IN} = input voltage

 (3)

Therefore, the inductor peak current is calculated with 公式 4.

(2)



$$I_{L(P)} = I_{L(DC)} + \frac{\Delta I_{L(P-P)}}{2} \tag{4}$$

Normally, it is advisable to work with an inductor peak-to-peak current of less than 40% of the average inductor current for maximum output current. A smaller ripple from a larger valued inductor reduces the magnetic hysteresis losses in the inductor, and EMI. But in the same way, load transient response time is increased. Because the TLV61046A is for relatively small output current application, the inductor peak-to-peak current could be as high as 200% of the average current with a small inductor value, which means the TLV61046A always works in DCM mode.表 2 lists the recommended inductors for the TLV61046A.

表 2. Recommended Inductors for the TLV61046A

PART NUMBER	L(µH)	DCR MAX (m Ω)	SATURATION CURRENT (A)	SIZE (LxWxH)	VENDOR ⁽¹⁾
FDSD0420-H-100M	10	200	2.5	4.2x4.2x2.0	Toko
CDRH3D23/HP	10	198	1.02	4.0x4.0x2.5	Sumida
74438336100	10	322	2.35	3.2x3.2x2.0	Wurth
VLS4012-4R7M	4.7	132	1.1	4.0x4.0x1.2	TDK

⁽¹⁾ See Third-party Products Disclaimer

8.2.2.3 Input and Output Capacitor Selection

The output capacitor is mainly selected to meet the requirements for output ripple and loop stability. This ripple voltage is related to the capacitor's capacitance and its equivalent series resistance (ESR). Assuming a ceramic capacitor with zero ESR, the minimum capacitance needed for a given ripple can be calculated by:

$$C_{OUT} = \frac{I_{OUT} \times D_{MAX}}{f_{SW} \times V_{RIPPLE}}$$

where

- D_{MAX} = maximum switching duty cycle
- V_{RIPPLE} = peak to peak output voltage ripple

The ESR impact on the output ripple must be considered if tantalum or aluminum electrolytic capacitors are used.

Care must be taken when evaluating a ceramic capacitor's derating under dc bias, aging, and ac signal. For example, the dc bias can significantly reduce capacitance. A ceramic capacitor can lose more than 50% of its capacitance at its rated voltage. Therefore, always leave margin on the voltage rating to ensure adequate capacitance at the required output voltage.

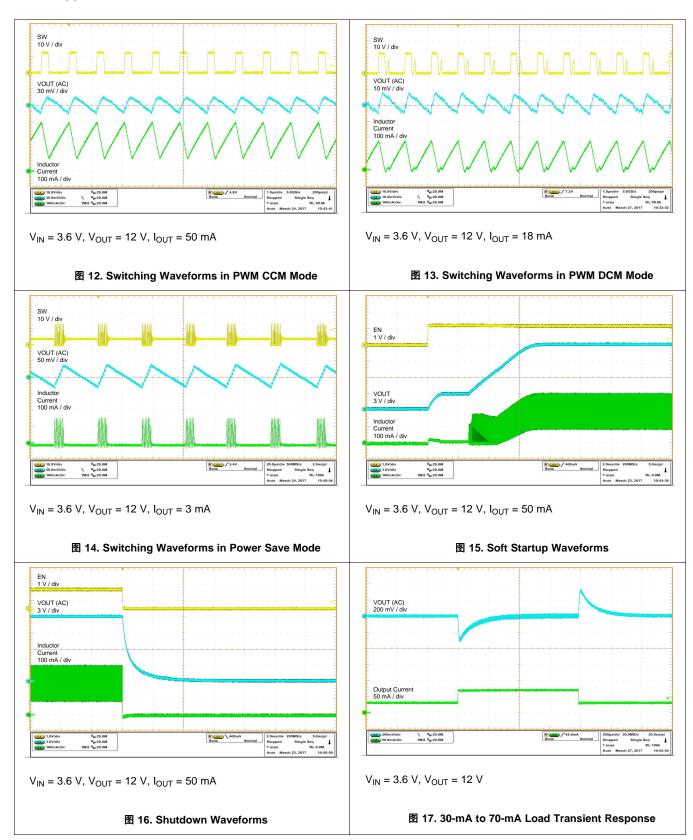
It is recommended to use the output capacitor with effective capacitance in the range of 0.47 μ F to 10 μ F. The output capacitor affects loop stability of the boost regulator. If the output capacitor is below the range, the boost regulator can potentially become unstable. Increasing the output capacitor makes the output voltage ripple smaller in PWM mode.

For input capacitor, a ceramic capacitor with more than 1.0 µF is enough for most applications.

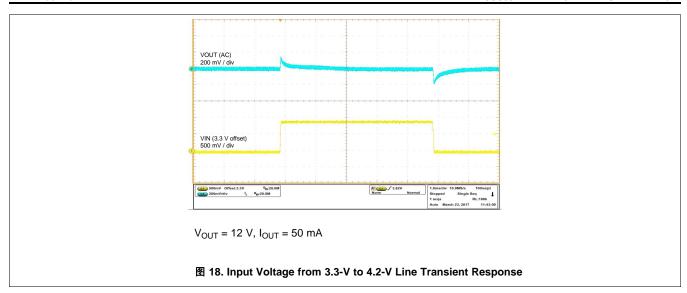
(5)

TEXAS INSTRUMENTS

8.2.3 Application Performance Curves



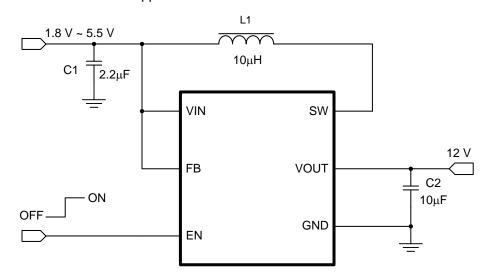




8.3 System Examples

8.3.1 Fixed 12-V Output Voltage with Three External Components

The TLV61046A can output fixed 12-V voltage by connecting the FB pin to the VIN pin to save the external resistor divider. The ₹ 19 shows the application circuit.



Copyright © 2017, Texas Instruments Incorporated

图 19. Fixed 12-V Output Voltage by Connecting the FB Pin to VIN Pin



9 Power Supply Recommendations

The device is designed to operate from an input voltage supply range between 1.8 V to 5.5 V. This input supply must be well regulated. If the input supply is located more than a few inches from the converter, additional bulk capacitance may be required in addition to the ceramic bypass capacitors. A typical choice is an electrolytic or tantalum capacitor with a value of 47 μ F. The input power supply's output current needs to be rated according to the supply voltage, output voltage and output current of the TLV61046A.



10 Layout

10.1 Layout Guidelines

As for all switching power supplies, especially those running at high switching frequency and high currents, layout is an important design step. If the layout is not carefully done, the regulator could suffer from instability and noise problems. To maximize efficiency, switch rise and fall time are very fast. To prevent radiation of high frequency noise (for example, EMI), proper layout of the high-frequency switching path is essential. Minimize the length and area of all traces connected to the SW pin, and always use a ground plane under the switching regulator to minimize interplane coupling. The input capacitor needs not only to be close to the VIN pin, but also to the GND pin in order to reduce input supply ripple.

The most critical current path for all boost converters is from the switching FET, through the rectifier diode, then the output capacitors, and back to ground of the switching FET. This high current path contains nanosecond rise and fall time and should be kept as short as possible. Therefore, the output capacitors need not only to be close to the VOUT pin, but also to the GND pin to reduce the overshoot at the SW pin and VOUT pin.

10.2 Layout Example

A large ground plane on the bottom layer connects the ground pins of the components on the top layer through vias.

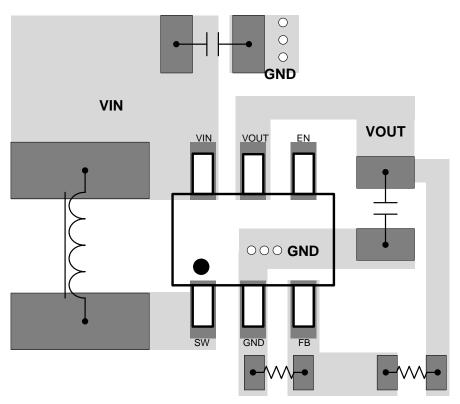


图 20. PCB Layout Example



11 器件和文档支持

11.1 器件支持

11.1.1 Third-Party Products Disclaimer

TI'S PUBLICATION OF INFORMATION REGARDING THIRD-PARTY PRODUCTS OR SERVICES DOES NOT CONSTITUTE AN ENDORSEMENT REGARDING THE SUITABILITY OF SUCH PRODUCTS OR SERVICES OR A WARRANTY, REPRESENTATION OR ENDORSEMENT OF SUCH PRODUCTS OR SERVICES, EITHER ALONE OR IN COMBINATION WITH ANY TI PRODUCT OR SERVICE.

11.2 接收文档更新通知

要接收文档更新通知,请导航至德州仪器 Tl.com.cn 上的器件产品文件夹。请单击右上角的*通知我* 进行注册,即可 收到任意产品信息更改每周摘要。有关更改的详细信息,请查看任意已修订文档中包含的修订历史记录。

11.3 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商"按照原样"提供。这些内容并不构成 TI 技术规范, 并且不一定反映 TI 的观点:请参阅 TI 的 《使用条款》。

TI E2E™ 在线社区 TI 的工程师对工程师 (E2E) 社区。此社区的创建目的在于促进工程师之间的协作。在 e2e.ti.com 中,您可以咨询问题、分享知识、拓展思路并与同行工程师一道帮助解决问题。

TI 参考设计支持 可帮助您快速查找有帮助的 E2E 论坛、设计支持工具以及技术支持的联系信息。 设计支持

11.4 商标

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

11.5 静电放电警告



ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序,可 能会损坏集成电路。



▲ SSD 的损坏小至导致微小的性能降级,大至整个器件故障。 精密的集成电路可能更容易受到损坏,这是因为非常细微的参数更改都可 能会导致器件与其发布的规格不相符。

11.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

以下页面包括机械、封装和可订购信息。这些信息是指定器件的最新可用数据。这些数据发生变化时,我们可能不 会另行通知或修订此文档。如欲获取此产品说明书的浏览器版本,请参阅左侧的导航栏。



PACKAGE OPTION ADDENDUM

15-Aug-2017

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
TLV61046ADBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	1C4F	Samples
TLV61046ADBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	1C4F	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.





15-Aug-2017

PACKAGE MATERIALS INFORMATION

www.ti.com 15-Aug-2017

TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLV61046ADBVR	SOT-23	DBV	6	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TLV61046ADBVT	SOT-23	DBV	6	250	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

www.ti.com 15-Aug-2017

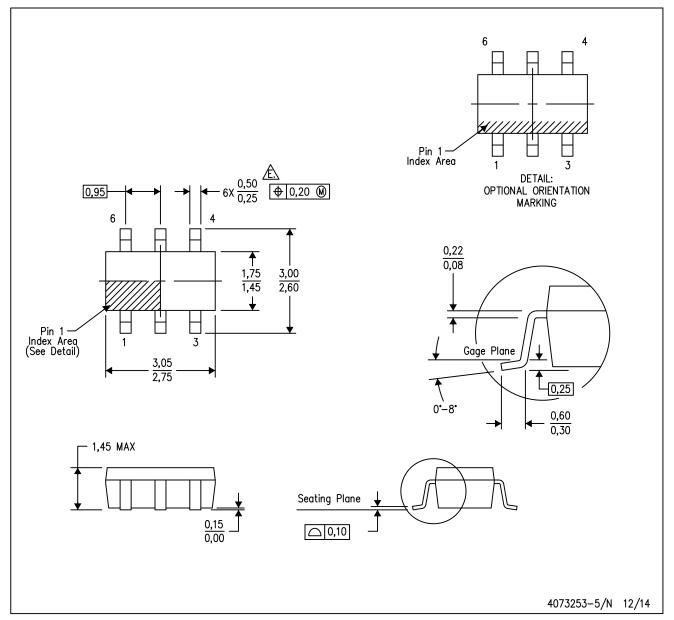


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
TLV61046ADBVR	SOT-23	DBV	6	3000	210.0	185.0	35.0	
TLV61046ADBVT	SOT-23	DBV	6	250	210.0	185.0	35.0	

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.



重要声明

德州仪器 (TI) 公司有权按照最新发布的 JESD46 对其半导体产品和服务进行纠正、增强、改进和其他修改,并不再按最新发布的 JESD48 提供任何产品和服务。买方在下订单前应获取最新的相关信息,并验证这些信息是否完整且是最新的。

TI 公布的半导体产品销售条款 (http://www.ti.com/sc/docs/stdterms.htm) 适用于 TI 己认证和批准上市的已封装集成电路产品的销售。另有其他条款可能适用于其他类型 TI 产品及服务的使用或销售。

复制 TI 数据表上 TI 信息的重要部分时,不得变更该等信息,且必须随附所有相关保证、条件、限制和通知,否则不得复制。TI 对该等复制文件不承担任何责任。第三方信息可能受到其它限制条件的制约。在转售 TI 产品或服务时,如果存在对产品或服务参数的虚假陈述,则会失去相关 TI 产品或服务的明示或暗示保证,且构成不公平的、欺诈性商业行为。TI 对此类虚假陈述不承担任何责任。

买方和在系统中整合 TI 产品的其他开发人员(总称"设计人员")理解并同意,设计人员在设计应用时应自行实施独立的分析、评价和判断,且应全权负责并确保应用的安全性,及设计人员的应用(包括应用中使用的所有 TI 产品)应符合所有适用的法律法规及其他相关要求。设计人员就自己设计的应用声明,其具备制订和实施下列保障措施所需的一切必要专业知识,能够(1)预见故障的危险后果,(2)监视故障及其后果,以及(3)降低可能导致危险的故障几率并采取适当措施。设计人员同意,在使用或分发包含 TI 产品的任何应用前,将彻底测试该等应用和该等应用中所用 TI 产品的功能。

TI 提供技术、应用或其他设计建议、质量特点、可靠性数据或其他服务或信息,包括但不限于与评估模块有关的参考设计和材料(总称"TI 资源"),旨在帮助设计人员开发整合了 TI 产品的 应用, 如果设计人员(个人,或如果是代表公司,则为设计人员的公司)以任何方式下载、访问或使用任何特定的 TI 资源,即表示其同意仅为该等目标,按照本通知的条款使用任何特定 TI 资源。

TI 所提供的 TI 资源,并未扩大或以其他方式修改 TI 对 TI 产品的公开适用的质保及质保免责声明;也未导致 TI 承担任何额外的义务或责任。TI 有权对其 TI 资源进行纠正、增强、改进和其他修改。除特定 TI 资源的公开文档中明确列出的测试外,TI 未进行任何其他测试。

设计人员只有在开发包含该等 TI 资源所列 TI 产品的 应用时, 才被授权使用、复制和修改任何相关单项 TI 资源。但并未依据禁止反言原则或其他法理授予您任何TI知识产权的任何其他明示或默示的许可,也未授予您 TI 或第三方的任何技术或知识产权的许可,该等产权包括但不限于任何专利权、版权、屏蔽作品权或与使用TI产品或服务的任何整合、机器制作、流程相关的其他知识产权。涉及或参考了第三方产品或服务的信息不构成使用此类产品或服务的许可或与其相关的保证或认可。使用 TI 资源可能需要您向第三方获得对该等第三方专利或其他知识产权的许可。

TI 资源系"按原样"提供。TI 兹免除对资源及其使用作出所有其他明确或默认的保证或陈述,包括但不限于对准确性或完整性、产权保证、无屡发故障保证,以及适销性、适合特定用途和不侵犯任何第三方知识产权的任何默认保证。TI 不负责任何申索,包括但不限于因组合产品所致或与之有关的申索,也不为或对设计人员进行辩护或赔偿,即使该等产品组合已列于 TI 资源或其他地方。对因 TI 资源或其使用引起或与之有关的任何实际的、直接的、特殊的、附带的、间接的、惩罚性的、偶发的、从属或惩戒性损害赔偿,不管 TI 是否获悉可能会产生上述损害赔偿,TI 概不负责。

除 TI 己明确指出特定产品已达到特定行业标准(例如 ISO/TS 16949 和 ISO 26262)的要求外,TI 不对未达到任何该等行业标准要求而承担任何责任。

如果 TI 明确宣称产品有助于功能安全或符合行业功能安全标准,则该等产品旨在帮助客户设计和创作自己的 符合 相关功能安全标准和要求的应用。在应用内使用产品的行为本身不会 配有 任何安全特性。设计人员必须确保遵守适用于其应用的相关安全要求和 标准。设计人员不可将任何 TI 产品用于关乎性命的医疗设备,除非己由各方获得授权的管理人员签署专门的合同对此类应用专门作出规定。关乎性命的医疗设备是指出现故障会导致严重身体伤害或死亡的医疗设备(例如生命保障设备、心脏起搏器、心脏除颤器、人工心脏泵、神经刺激器以及植入设备)。此类设备包括但不限于,美国食品药品监督管理局认定为 III 类设备的设备,以及在美国以外的其他国家或地区认定为同等类别设备的所有医疗设备。

TI 可能明确指定某些产品具备某些特定资格(例如 Q100、军用级或增强型产品)。设计人员同意,其具备一切必要专业知识,可以为自己的应用选择适合的 产品, 并且正确选择产品的风险由设计人员承担。设计人员单方面负责遵守与该等选择有关的所有法律或监管要求。

设计人员同意向 TI 及其代表全额赔偿因其不遵守本通知条款和条件而引起的任何损害、费用、损失和/或责任。

邮寄地址: 上海市浦东新区世纪大道 1568 号中建大厦 32 楼,邮政编码: 200122 Copyright © 2017 德州仪器半导体技术(上海)有限公司